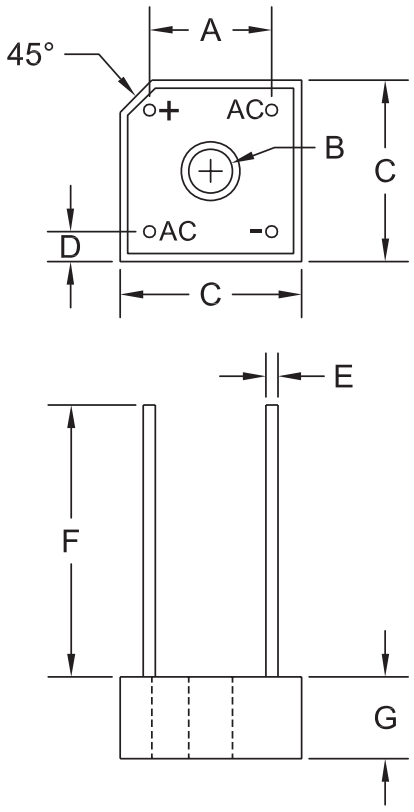
Package Details - CASE CM

Mechanical Drawing

Mechanical Drawing: CASE CM



DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.405	0.445	10.29	11.30
B	0.142	0.158	3.60	4.01
C	0.580	0.620	14.73	15.75
D	0.067	0.107	1.70	2.72
E	0.040		1.02	
F	0.748	-	19.00	-
G	0.230	0.272	5.84	6.90

CASE CM (REV: R1)

Lead Code:
As marked

R1

Packing options:

Bulk - Packing Code: B
B = White corrugated box with black conductive lining and bridge inserts (surface resistivity of $<10^5$ ohms per square).
Bulk Packing Quantity: 400

Material Composition Specification

Case CM

Device average mass . . . . . **3.0 g**

Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.52%	15.59	Si	7440-21-3	0.51%	15.56	5,187
				Au	7440-57-5	0.01%	0.03	10
leadframe	copper	36.64%	1,099	Cu	7440-50-8	36.64%	1,099	366,353
die attach	high temperature solder	0.45%	13.61	Pb	7439-92-1	<0.001%	0.002	1
				Sn	7440-31-5	0.45%	13.608	4,536
encapsulation	EMC	60.83%	1,825	epoxy resin	Proprietary	60.83%	1,825	608,333
plating*	tin/lead process	1.56%	46.74	Sn	74401-31-5	1.25%	37.40	12,464
				Pb	7439-92-1	0.31%	9.34	3,116
	100% tin process	1.56%	46.74	Sn	7440-31-5	1.56%	46.74	15,580

*For Lead Free plating, add suffix “LEAD FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.